

MOS FIELD EFFECT TRANSISTOR NP82N03PUG

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The NP82N03PUG is N-channel MOS Field Effect

Transistor designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE		
NP82N03PUG	TO-263 (MP-25ZP)		

FEATURES

- Channel temperature 175 degree rating
- Super low on-state resistance

 $R_{DS(on)} = 2.8 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = 10 \text{ V, Ip} = 41 \text{ A)}$

• Low Ciss: Ciss = 6050 pF TYP.

(TO-263)



ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (V _{GS} = 0 V)	VDSS	30	V
Gate to Source Voltage (V _{DS} = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	ID(DC)	±82	Α
Drain Current (pulse) Note1	D(pulse)	±328	Α
Total Power Dissipation (T _A = 25°C)	P _{T1}	1.8	W
Total Power Dissipation (Tc = 25°C)	P _{T2}	143	W
Channel Temperature	Tch	175	°C
Storage Temperature	Tstg	-55 to +175	°C
Repetitive Avalanche Current Note2	I AR	47	Α
Repetitive Avalanche Energy Note2	Ear	221	mJ

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Tch \leq 150°C, VDD = 15 V, Rg = 25 Ω , Vgs = 20 \rightarrow 0 V

THERMAL RESISTANCE

Channel to Case Thermal Resistance	Rth(ch-C)	1.05	°C/W
Channel to Ambient Thermal Resistance	Rth(ch-A)	83.3	°C/W

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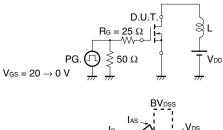


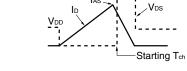
ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 30 V, V _{GS} = 0 V			1.0	μΑ
Gate Leakage Current	Igss	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA
Gate to Source Threshold Voltage Note	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.0	3.0	4.0	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 41 A	19	39		S
Drain to Source On-state Resistance Note	RDS(on)	V _{GS} = 10 V, I _D = 41 A		2.1	2.8	mΩ
Input Capacitance	Ciss	V _{DS} = 25 V		6050	9080	pF
Output Capacitance	Coss	V _{GS} = 0 V		700	1050	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		480	870	pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15 V, I _D = 41 A		39	90	ns
Rise Time	tr	V _{GS} = 10 V		122	310	ns
Turn-off Delay Time	t _{d(off)}	R _G = 0 Ω		70	140	ns
Fall Time	tf			15	40	ns
Total Gate Charge	Q _G	V _{DD} = 24 V		106	160	nC
Gate to Source Charge	Qgs	V _{GS} = 10 V		28		nC
Gate to Drain Charge	Q _{GD}	I _D = 82 A		39		nC
Body Diode Forward Voltage Note	V _F (S-D)	I _F = 82 A, V _{GS} = 0 V		0.9	1.5	V
Reverse Recovery Time	trr	I _F = 82 A, V _{GS} = 0 V		44		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		41		nC

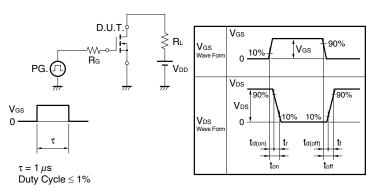
Note Pulsed

TEST CIRCUIT 1 AVALANCHE CAPABILITY



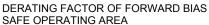


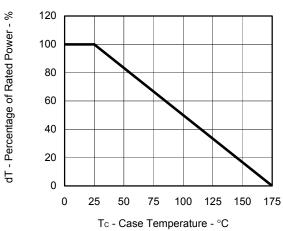
TEST CIRCUIT 2 SWITCHING TIME



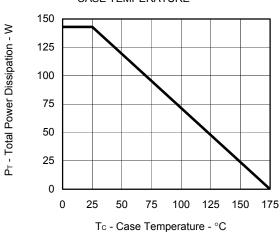
TEST CIRCUIT 3 GATE CHARGE

TYPICAL CHARACTERISTICS (TA = 25°C)

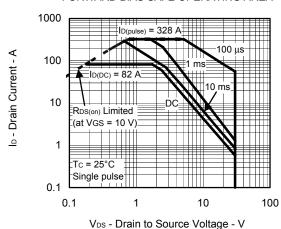




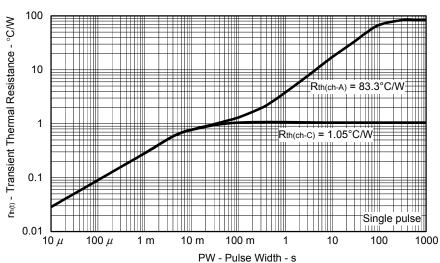
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



FORWARD BIAS SAFE OPERATING AREA

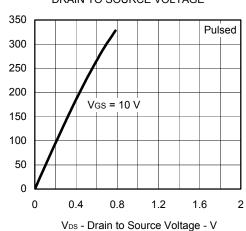


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

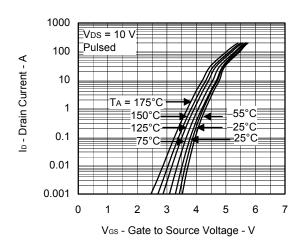


lo - Drain Current - A

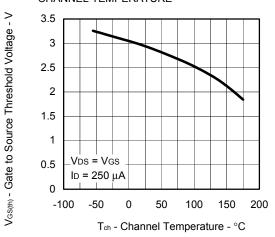
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



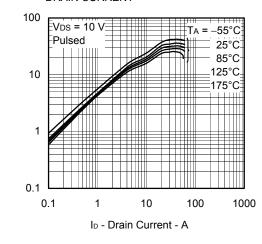
FORWARD TRANSFER CHARACTERISTICS



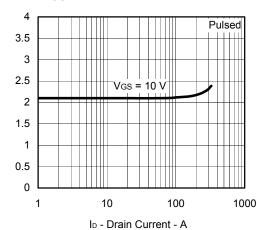
GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE



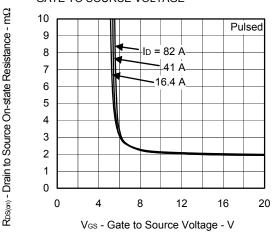
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



R_{DS(m)} - Drain to Source On-state Resistance - mΩ

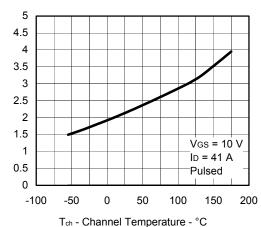
y_{fs} | - Forward Transfer Admittance - S

Res_(on) - Drain to Source On-state Resistance - mΩ

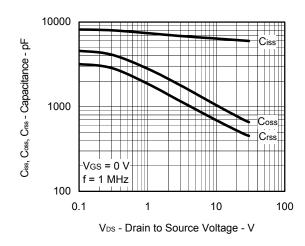
ta(on), tr, ta(off), tr - Switching Time - ns

F - Diode Forward Current - A

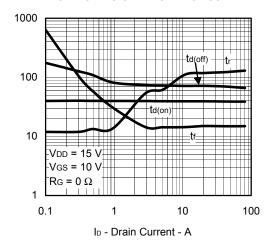
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



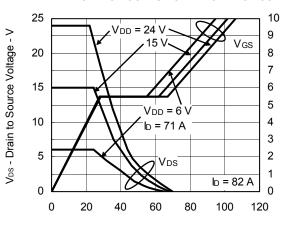
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



SWITCHING CHARACTERISTICS

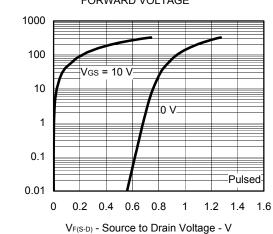


DYNAMIC INPUT/OUTPUT CHARACTERISTICS

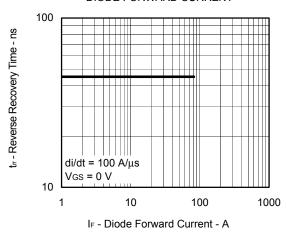


Q_G - Gate Charge - nC

SOURCE TO DRAIN DIODE FORWARD VOLTAGE



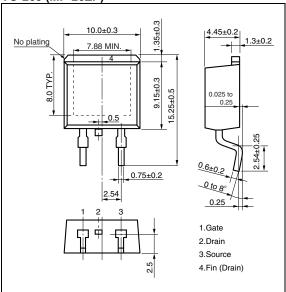
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



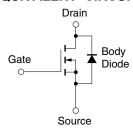
Ves - Gate to Source Voltage - V

PACKAGE DRAWING (Unit: mm)

TO-263 (MP-25ZP)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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